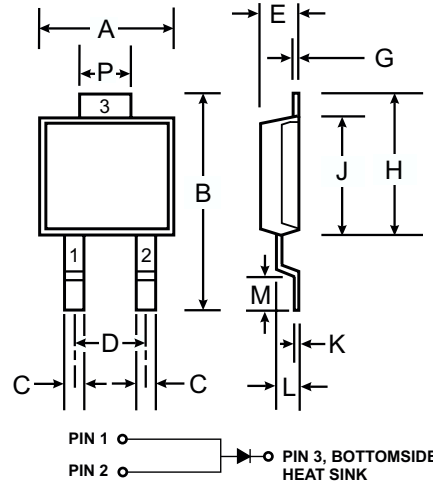


**Features**

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Low Reverse Current
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications

**Mechanical Data**

- Case: POWERMITE®3, Molded Plastic
- Plastic Material: UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Marking: See Page 3
- Weight: 0.072 grams (approx.)
- Ordering Information: See Page 3



POWERMITE®3		
Dim	Min	Max
A	4.03	4.09
B	6.40	6.61
C	.889 NOM	
D	1.83 NOM	
E	1.10	1.14
G	.178 NOM	
H	5.01	5.17
J	4.37	4.43
K	.178 NOM	
L	.71	.77
M	.36	.46
P	1.73	1.83
All Dimensions in mm		

Note: Pins 1 & 2 must be electrically connected at the printed circuit board.

**Maximum Ratings** @ T<sub>A</sub> = 25°C unless otherwise specified

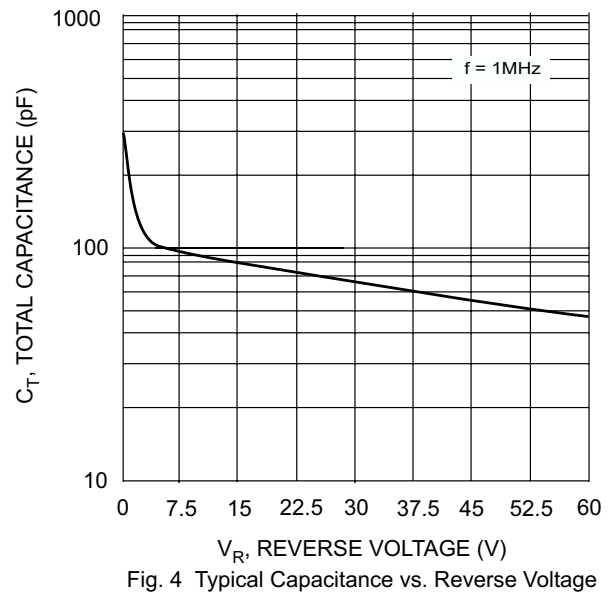
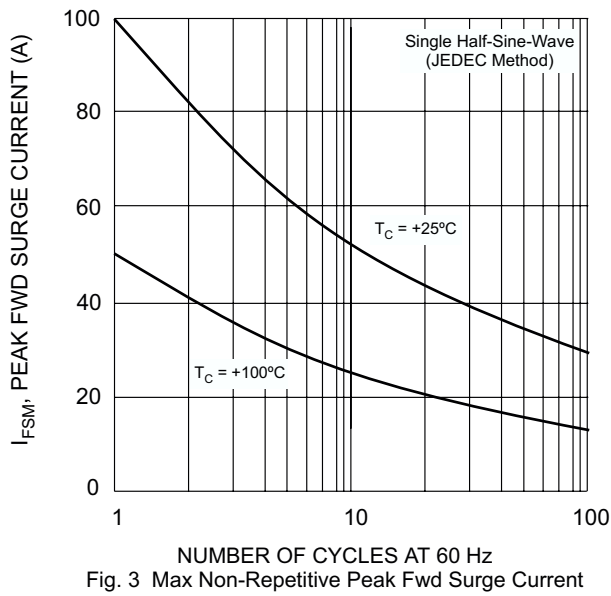
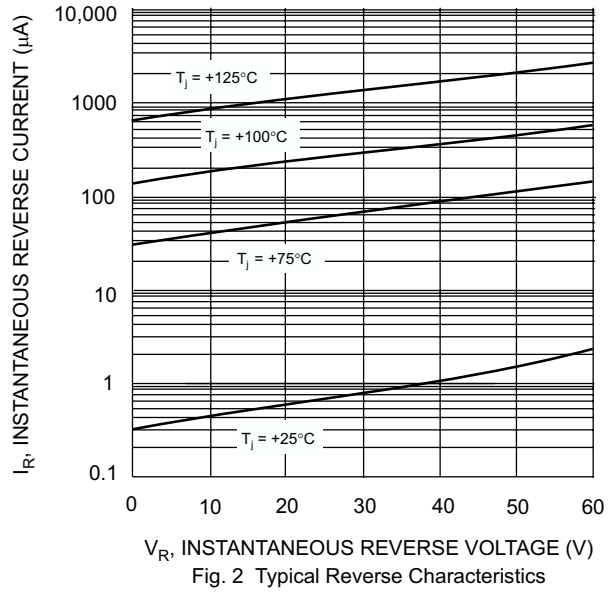
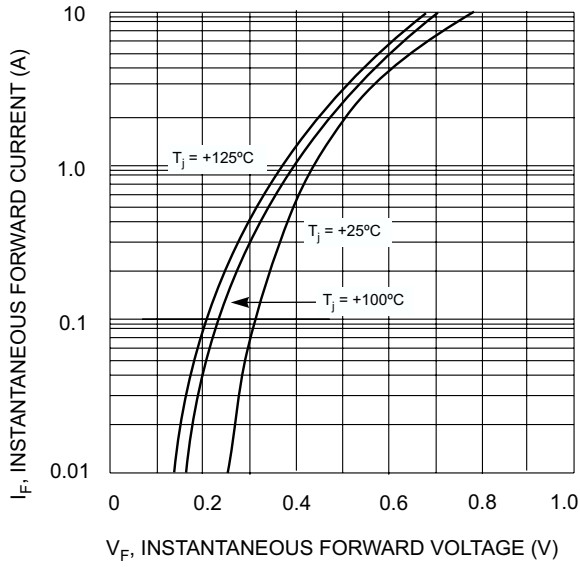
Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	60	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	42	V
Average Rectified Output Current (See also Figure 5)	I <sub>O</sub>	3	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	100 50	A
		@ T <sub>C</sub> = 25°C @ T <sub>C</sub> = 100°C	
Typical Thermal Resistance Junction to Soldering Point	R <sub>θJS</sub>	3.2	°C/W
Operating Temperature Range	T <sub>j</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	V <sub>(BR)R</sub>	60	—	—	V	I <sub>R</sub> = 0.2mA
Forward Voltage (Note 1)	V <sub>FM</sub>	—	0.59 0.53 0.72 0.63	0.63 0.57 0.76 0.67	V	I <sub>F</sub> = 3A, T <sub>j</sub> = 25°C I <sub>F</sub> = 3A, T <sub>j</sub> = 125°C I <sub>F</sub> = 6A, T <sub>j</sub> = 25°C I <sub>F</sub> = 6A, T <sub>j</sub> = 125°C
Reverse Current (Note 1)	I <sub>RM</sub>	—	2.0 0.6 2.5	200 20 150	µA mA mA	T <sub>j</sub> = 25°C, V <sub>R</sub> = 60V T <sub>j</sub> = 100°C, V <sub>R</sub> = 60V T <sub>j</sub> = 125°C, V <sub>R</sub> = 60V
Total Capacitance	C <sub>T</sub>	—	130	—	pF	f = 1.0MHz, V <sub>R</sub> = 4.0V DC

Notes: 1. Short duration test pulse used to minimize self-heating effect.



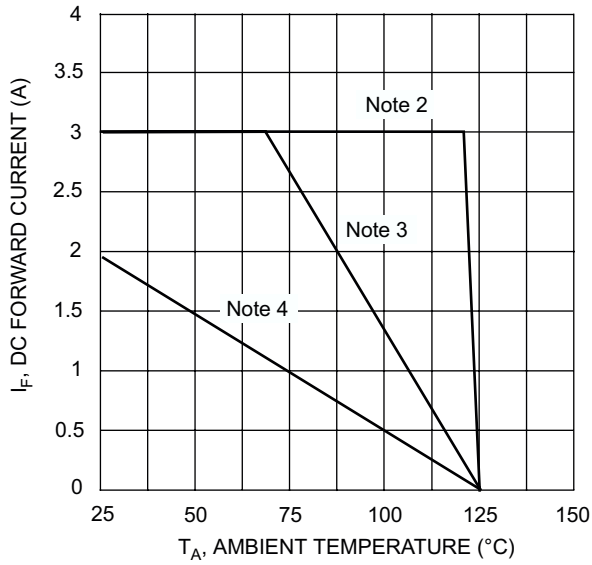


Fig. 5 DC Forward Current Derating

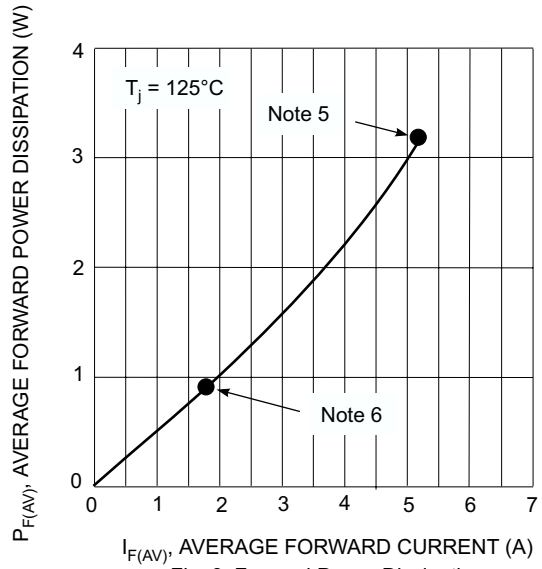


Fig. 6 Forward Power Dissipation

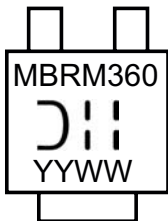
- Notes:
- $T_A = T_{\text{SOLDERING POINT}}$ ,  $R_{\theta JS} = 3.2^\circ\text{C/W}$ ,  $R_{\theta SA} = 0^\circ\text{C/W}$ .
  - Device mounted on GETEK substrate, 2"x2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0".  $R_{\theta JA}$  in range of 20-40°C/W.
  - Device mounted on FR-4 substrate, 2"x2", 2 oz. copper, single-sided, pad layout as per Diodes Inc. suggested pad layout document AP02001 which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.  $R_{\theta JA}$  in range of 100-120°C/W.
  - Maximum power dissipation when the device is mounted in accordance to the conditions described in Note 3.
  - Maximum power dissipation when the device is mounted in accordance to the conditions described in Note 4.

### Ordering Information (Note 7)

Device	Packaging	Shipping
MBRM360-13	POWERMITE®3	5000/Tape & Reel

- Notes: 7. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

### Marking Information



- MBRM360 = Product type marking code  
 = Manufacturers' code marking  
 YYWW = Date code marking  
 YY = Last digit of year ex: 2 for 2002  
 WW = Week code 01 to 52